

# Typical Specifications

Ite	ms	Specifications		
Rating (max.)/(min.) (Resistive load)		0.2A 30V DC / 50 μA 3V DC		
Contact resistand (Initial/After opera	-	$20$ m $\Omega$ max. / $40$ m $\Omega$ max.		
0	1-pole	2.3±1N		
Operating force	2-pole	3.3±1N		
Operating life	Without load	10,000 cycles		
Operating life	With load	10,000 cycles (0.2A 30V DC)		

### Product Line

Changeove	r Trav (mn		Total travel (mm)	Mounting method	Poles	Operation	Terminal type	Minimum ord Japan	er unit (pcs.) Export	Product No.	Drawing No.		
tiriii 18	(11111	17	(11111)	metriod			суро	Japan	LXPUIT		140.		
					,	Latching				SPPJ310500	1		
Non shorting 2	~ 0.5	2.5	0.5	PC board	'	Momentary	For	000	4.500	SPPJ311500			
	g 2.5		2.5 3.5	5 3.5 PCD	PC board	0	Latching	PC board	PC board 900	900	4,500	SPPJ320600	0
							2		Momentary			SPPJ322300	2

# Packing Specifications

### Bulk

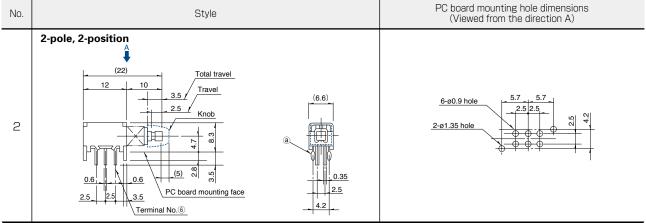
Number of pa	ckages (pcs.)	Export package measurements	
1 case / Japan 1 case / export packing		(mm)	
900	4,500	400×270×290	

Dimensions PC board mounting hole dimensions (Viewed from the direction A) Style No. 1-pole, 2-position Total travel 3-ø0.9 hole 2-ø1.2 hole 1

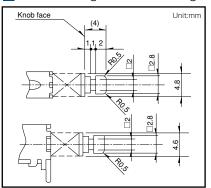
### Dimensions

Unit:mm

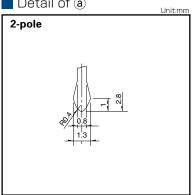
2.5mm-travel Compact-sized Horizontal Type



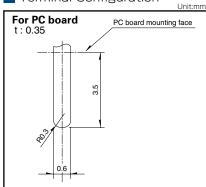
# Actuator Configuration at Front Edge



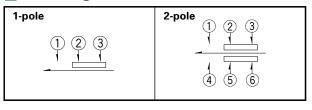


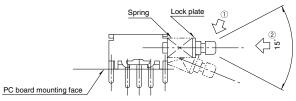


# Terminal Configuration



# Circuit Diagram (Viewed from Direction A)





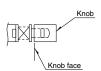
The SPPJ3 series should be operated in arrow 2 direction as shown in the following figure and applied within an angle of 15° based from the center. If excessive force is applied to the lever from arrow ① direction, it may fall down as illustrated and cause malfunctions.

### Attached Parts

Attacrica raits		Unit:mm
Knob outline drawing	Model	
4.6	Color:Black	UJ206022
		UJ206022

### Notes

- 1. Other knob varieties are also available. Please inquire.
- 2. We recommend the use of adhesive to secure the knob when mounting onto switches.





			Horizontal							
	Series		SPPJ3	SPPJ2	SPUJ	SPUN	SPUN medium current			
	Photo									
W		5 or 6.6	7.2	7.5		10				
Dimensio (mm)			1	12		24 36				
		Н	8.3	9.6	8.8	8.8 13				
Tra	vel (mm)		2	.5	2	2	2.5			
Total	travel (m	m)	3	.5	3	3	3.5			
Numb	er of pol	es	1 2	2		2 4				
	perating rature rai	nge	-40℃ to +85℃		-10℃ to	0 +60℃				
Auto	motive us	se	•	•	_					
Li	fe cycle		<b>*</b> 3	**3	*3	₹3				
Rati (Resi	Rating (max.) (Resistive load) 0.2A 30V DC 0.1A 30V DC				1A 25V DC					
Rat (Resi	ng (min.) stive loa	) d)		50μΑ	3V DC		_			
Durability		ting life ut load	10,000 cycles 40mΩ max. 30,000 cycles 40mΩ max.			10,000 cycles 40mΩ max.				
Durability		ife with load rated load)		10,000 cycle	s 40mΩ max.		5,000 cycles 40mΩ max.			
		contact tance			20mΩ max.					
Electrical performance		ation tance	100MΩ min. 500V DC							
	Voltag	e proof			500V AC for 1minute					
		ninal ngth			5N for 1minute					
Mechanical performance	Actuator strength	Operating direction	50N	30N		50N				
		Pulling direction	_	_		50N				
	Co	old	-40°C 96h -20°C 96h							
Environmental performance	Dry heat		85°C 96h							
	Damp	) heat	40°C, 90 to 95%RH 96h							
	Page		111	113	115	1	17			

### NI I

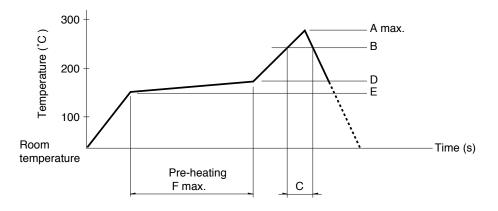
• Indicates applicability to all products in the series.

# ■ Example of Reflow Soldering Condition

- 1. Heating method: Double heating method with infrared heater.
- 2. Temperature measurement: Thermocouple  $\phi$  0.1 to 0.2 CA (K) or CC (T) at soldering portion (copper foil surface). A heat resisting tape should be used for fixed measurement.

Push Switches / Soldering Conditions

3. Temperature profile



Series (Reflow type)	A (℃) 3s max.	B (℃)	C (s)	D (°C)	E (℃)	F(s)
SPEJ						
SPEF	260	230	40	180	150	120
SPEH						

### Notes

- 1. The condition mentioned above is the temperature on the mounting surface of a PC board. There are cases where the PC board's temperature greatly differs from that of the switch, depending on the PC board's material, size, thickness, etc.

  The above-stated conditions shall also apply to switch surface temperatures.
- 2. Soldering conditions differ depending on reflow soldering machines. Prior verification of soldering condition is highly recommended.

### Reference for Hand Soldering

Series	Soldering temperature	Soldering time	
SPPJ3, SPPJ2, SPUN, SPPH4, SPPH1	350±10℃	3+1/0s	
SPED2, SPED4	350±10℃	3±0.5s	
SPEJ	350±10℃	4s max.	
SPEF	350±5℃	3s max.	
SPEH	350°C max.	3s max.	
SPUJ	300±10℃	3+1/0s	

# Reference for Dip Soldering (For PC board terminal types)

Series	Ite	ms	Dip soldering		
Jenes	Preheating temperature	Preheating time	Soldering temperature	Duration of immersion	
SPPJ3	100℃ max.	60s max.	260±5℃	5±1s	
SPUN	100°C max.	60s max.	260±5℃	10±1s	
SPUJ, SPPH4	_		260±5℃	5±1s	
SPPJ2, SPPH1, SPED2, SPED4, SPEF	_		260±5℃	10±1s	

